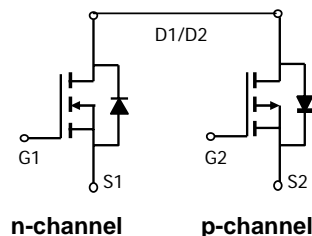
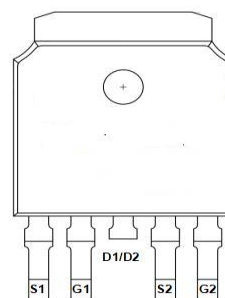
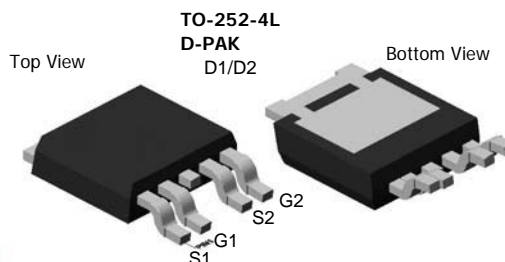


Features

- 20V, 65A
 $R_{DS(ON)}$ Typ = 5.0m Ω @ $V_{GS} = 4.5V$
 $R_{DS(ON)}$ Typ = 7.0m Ω @ $V_{GS} = 2.5V$
- -20V, -65A
 $R_{DS(ON)}$ Typ = 5.0m Ω @ $V_{GS} = -4.5V$
 $R_{DS(ON)}$ Typ = 7.0m Ω @ $V_{GS} = -2.5V$
- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge



Application

- Load Switch
- PWM Application
- Power Management

Absolute Maximum Ratings (@ $T_J = 25^\circ C$ unless otherwise specified)

Symbol	Parameter	N-Channel Value	P-Channel Value	Units
V_{DS}	Drain-to-Source Voltage	20	-20	V
V_{GS}	Gate-to-Source Voltage	± 12	± 12	V
I_D	Continuous Drain Current	$T_C = 25^\circ C$	65	-65
		$T_C = 100^\circ C$	38	-38
I_{DM}	Pulsed Drain Current ⁽¹⁾	120	-120	A
E_{AS}	Single Pulsed Avalanche Energy ⁽²⁾	25	25	mJ
P_D	Power Dissipation	$T_C = 25^\circ C$	22.3	22.3
$R_{\theta JC}$	Thermal Resistance, Junction to Ambient	5.6	5.6	$^\circ C/W$
T_J, T_{STG}	Junction & Storage Temperature Range	-55 to 150		$^\circ C$

N-Channel Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	20	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 20\text{V}, V_{GS} = 0\text{V}$	-	-	1.0	μA
I_{GSS}	Gate-Body Leakage Current	$V_{DS} = 0\text{V}, V_{GS} = \pm 12\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	0.5	0.9	1.1	V
$R_{DS(ON)}$	Static Drain-Source ON-Resistance ⁽³⁾	$V_{GS} = 4.5\text{V}, I_D = 25\text{A}$	-	5.0	6.5	$\text{m}\Omega$
		$V_{GS} = 2.5\text{V}, I_D = 15\text{A}$	-	7.0	10	$\text{m}\Omega$
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{GS} = 0\text{V}, V_{DS} = 10\text{V},$ $f = 1\text{MHz}$	-	1935	-	pF
C_{oss}	Output Capacitance		-	287	-	pF
C_{riss}	Reverse Transfer Capacitance		-	265	-	pF
Q_g	Total Gate Charge	$V_{GS} = 0 \text{ to } 4.5\text{V}$ $V_{DS} = 10\text{V}, I_D = 20\text{A}$	-	23	-	nC
Q_{gs}	Gate Source Charge		-	4.6	-	nC
Q_{gd}	Gate Drain("Miller") Charge		-	6.5	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-On DelayTime	$V_{GS} = 4.5\text{V}, V_{DD} = 10\text{V}$ $I_D = 20\text{A}, R_{GEN} = 3\Omega$	-	12	-	ns
t_r	Turn-On Rise Time		-	33	-	ns
$t_{d(off)}$	Turn-Off DelayTime		-	48	-	ns
t_f	Turn-Off Fall Time		-	95	-	ns
Drain-Source Diode Characteristics and Max Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current		-	-	65	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	120	A
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0\text{V}, I_S = 30\text{A}$	-	-	1.2	V
t_{rr}	Body Diode Reverse Recovery Time	$I_F = 10\text{A}, di/dt = 100\text{A}/\mu\text{s}$	-	11	-	ns
Q_{rr}	Body Diode Reverse Recovery Charge		-	3	-	nC

P-Channel Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = -250\mu\text{A}, V_{GS} = 0\text{V}$	-30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -20\text{V}, V_{GS} = 0\text{V}$	-	-	-1.0	μA
I_{GSS}	Gate-Body Leakage Current	$V_{DS} = 0\text{V}, V_{GS} = \pm 12\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	-0.3	-0.8	-1.5	V
$R_{DS(ON)}$	Static Drain-Source ON-Resistance ⁽³⁾	$V_{GS} = -4.5\text{V}, I_D = -15\text{A}$	-	5.0	7.0	$\text{m}\Omega$
		$V_{GS} = -2.5\text{V}, I_D = -12\text{A}$	-	7.0	10	$\text{m}\Omega$
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{GS} = 0\text{V}, V_{DS} = -10\text{V},$ $f = 1\text{MHz}$	-	3947	-	pF
C_{oss}	Output Capacitance		-	499	-	pF
C_{riss}	Reverse Transfer Capacitance		-	451	-	pF
Q_g	Total Gate Charge	$V_{GS} = 0$ to -4.5V $V_{DS} = -10\text{V}, I_D = -15\text{A}$	-	46	-	nC
Q_{gs}	Gate Source Charge		-	7.3	-	nC
Q_{gd}	Gate Drain("Miller") Charge		-	9.9	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-On DelayTime	$V_{GS} = -10\text{V}, V_{DD} = -10\text{V}$ $I_D = -14\text{A}, R_{GEN} = 2.7\Omega$	-	10	-	ns
t_r	Turn-On Rise Time		-	59	-	ns
$t_{d(off)}$	Turn-Off DelayTime		-	111	-	ns
t_f	Turn-Off Fall Time		-	43	-	ns
Drain-Source Diode Characteristics and Max Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current		-	-	-65	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-120	A
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0\text{V}, I_S = -20\text{A}$	-	-	-1.2	V
t_{rr}	Body Diode Reverse Recovery Time	$I_F = -10\text{A}, di/dt = 100\text{A}/\mu\text{s}$	-	18	-	ns
Q_{rr}	Body Diode Reverse Recovery Charge		-	10	-	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
 2. E_{AS} condition: Starting $T_J=25^\circ\text{C}$, $V_{DD}=10\text{V}$, $V_G=4.5\text{V}$, $R_G=25\text{ohm}$, $L=0.5\text{mH}$, $I_{AS}=10\text{A}$
 E_{AS} condition: Starting $T_J=25^\circ\text{C}$, $V_{DD}=-10\text{V}$, $V_G=-4.5\text{V}$, $R_G=25\text{ohm}$, $L=0.5\text{mH}$, $I_{AS}=-10\text{A}$
 3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$.

Test Circuit

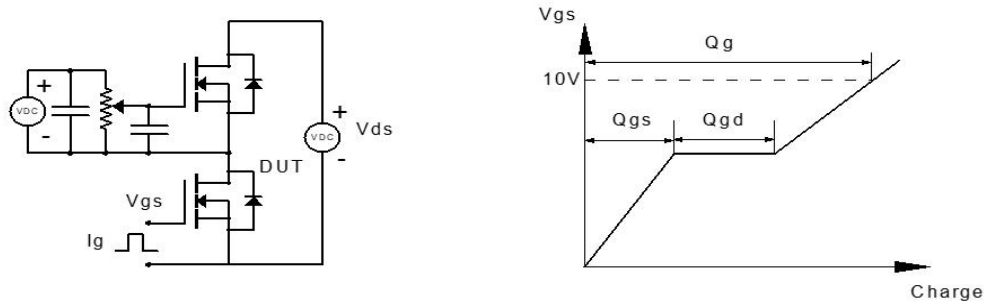


Figure 1: Gate Charge Test Circuit & Waveform

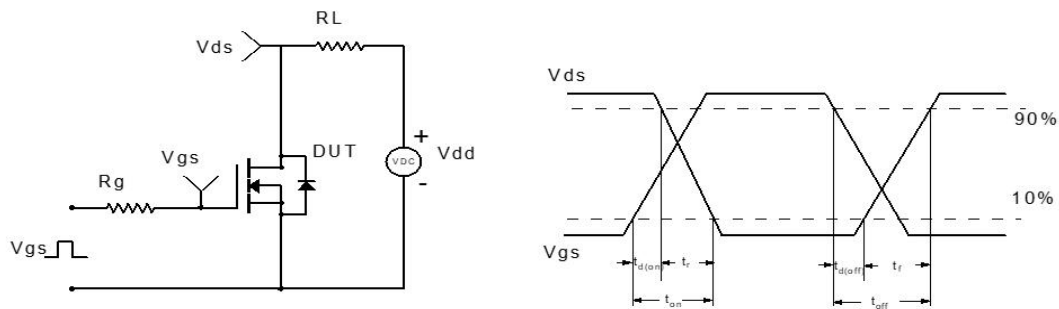


Figure 2: Resistive Switching Test Circuit & Waveform

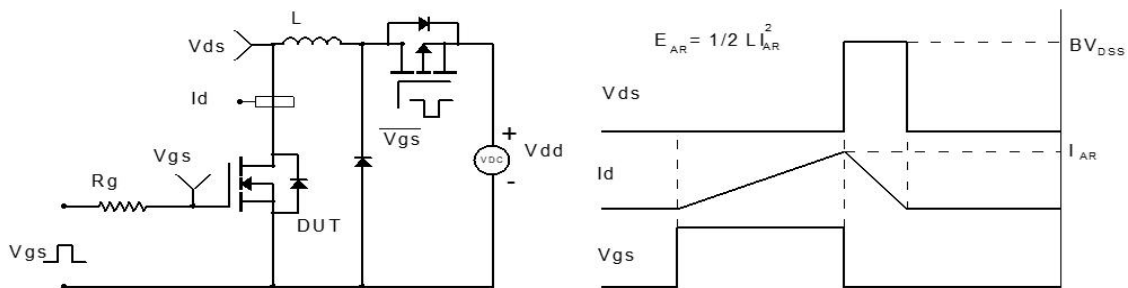


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

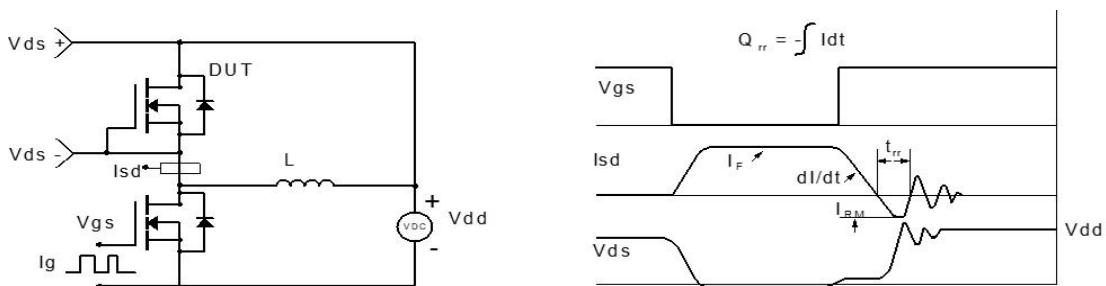
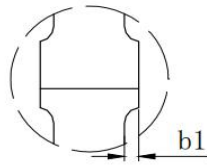
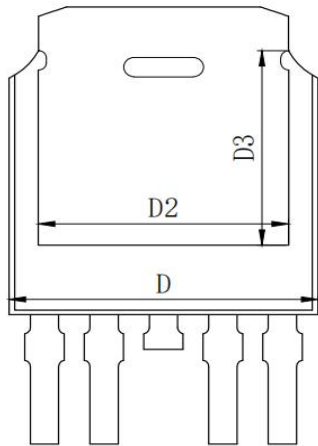
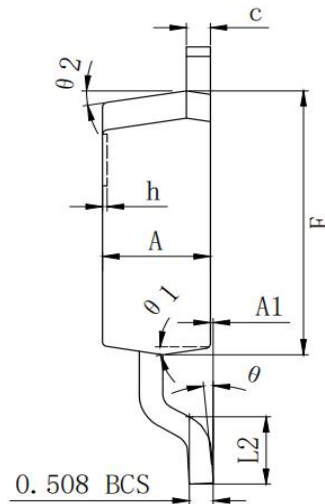
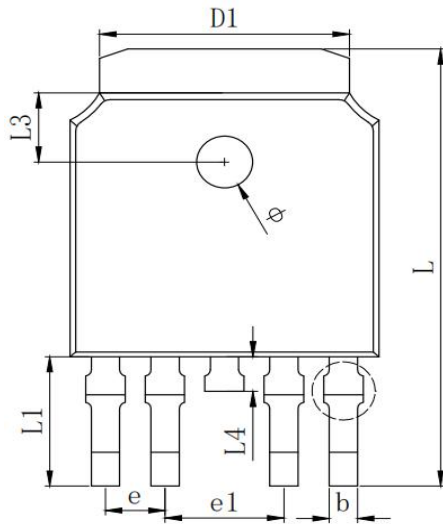


Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(TO-252-4L)



SYMBOL	MILLIMETER		
	MIN	Typ.	MAX
A	2.200	2.300	2.400
A1	0.000		0.127
b	0.550	0.600	0.650
b1	0.000		0.120
c (电镀后)	0.460	0.520	0.580
D	6.500	6.600	6.700
D1	5.334 REF		
D2	5.346 REF		
D3	4.490 REF		
E	6.000	6.100	6.200
e	1.270 TYP		
e1	2.540 TYP		
h	0.000	0.100	0.200
L	9.900	10.100	10.300
L1	2.988 REF		
L2	1.400	1.550	1.700
L3	1.600 REF		
L4	0.700	0.800	0.900
ϕ	1.100	1.200	1.300
θ	0°		8°
$\theta 1$	9° TYP		
$\theta 2$	9° TYP		